L Number				
1	150	6 card\$1 same (layer\$1 substrate\$1 base) same antenna same	DB	Time stamp
		(chip circuit ic module) same (adhesive glue\$1)	USPAT;	2002/10/18 11:5
		(auriesive glue\$1)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
2	23	(cardt) came (la la l		
		1 (Saidat Suille Havely) Chinerestagh basel	USPAT;	2002/40/40
		The should be included same (announce allocations)	US-PGPUB;	2002/10/18 11:4
	1	235/\$7.ccls.	EDO: IDO	
			EPO; JPO;	
3			DERWENT;	
	133		IBM_TDB	1
			USPAT;	2002/10/18 11:4
		same (laver\$1 substrate\$1 base) same (laver\$1) not ((card\$1	US-PGPUB;	, = , = 0
		same (layer\$1 substrate\$1 base) same antenna same (chip circuit ic module) same (adhesive sheet1)) not ((card\$1	EPO; JPO;	
		circuit ic module) same (adhesive glue\$1)) and 235/\$7.ccls.)	DERWENT;	1
4	4230		IBM_TDB	
		card\$1 same antenna same (chip circuit ic module)	USPAT;	2002/10/10 12:00
			US-PGPUB;	2002/10/18 12:00
			EPO; JPO;	
			DERWENT;	
5	4074	<i>t.</i>	IDM TOD	
	4074	(card\$1 same antenna same (chip circuit ic module)) not	IBM_TDB	
			USPAT;	2002/10/18 12:00
		(chip circuit ic module) same (adhesive glue\$1))	US-PGPUB;	
		(dditesive gide\$1))	EPO; JPO;	
			DERWENT;	
	407	((card\$1 same antenna same (chip circuit ic module)) not	IBM_TDB	
		(card\$1 same (layer\$1 substrate\$1 base) same antenna same (chip circuit ic module) same (adharing)	USPAT;	2002/10/18 12:00
		(chip circuit ic modulo) same (adha) same antenna same	US-PGPUB;	-502/10/10 12.00
		(chip circuit ic module) same (adhesive glue\$1))) and 235/\$7.ccls.	EPO; JPO;	
	1	/ 	DERWENT;	
	45	(((card\$1 camp anta-	IBM_TDB	
	.5	(((card\$1 same antenna same (chip circuit ic module)) not	USPAT:	2002/10/10 15 -
			US-PGPUB;	2002/10/18 12:01
1	1		EPO; JPO;	
	1	235/\$7.ccls.) and etch\$4	DEDWENT	
	10	//// Dis	DERWENT;	
	16	((((card\$1 same antenna same (chip circuit ic module)) not	IBM_TDB	
			USPAT;	2002/10/18 12:02
			US-PGPUB;	
		235/\$7.ccls.) and etch\$4) and resin	EPO; JPO;	
	1		DERWENT;	
	6	((card\$1 same antenna same (chip circuit ic module)) not	IBM_TDB	
	1.0	(card\$1 same (laver\$1 substrate\$1 to module)) not		2002/10/18 12:04
	1 i	(card\$1 same (layer\$1 substrate\$1 base) same antenna same	US-PGPUB;	
	1 '	chip circuit ic module) same (adhesive glue\$1))) same etch\$4	EPO; JPO;	
	"	outile (Calif	DERWENT;	
			IBM_TDB	
			TOIL I DD	